



Material Content Data Sheet



Sales Product Name		BTS7006-1EPP		Issued		4. July 2019		
MA#		MA002929138						
Package		PG-TSDSO-14-22		Weight*		65.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.001	1.54	1.54	15377	15377
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		579	
	non noble metal	iron	7439-89-6	0.754	1.16		11584	
wire	non noble metal	copper	7440-50-8	30.617	47.04	48.27	470361	482669
	non noble metal	copper	7440-50-8	0.668	1.03	1.03	10260	10260
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.13		1346
	plastics	epoxy resin	-	3.416	5.25		52477	
	inorganic material	silicondioxide	60676-86-0	25.692	39.47	44.85	394696	448519
leadfinish	non noble metal	tin	7440-31-5	1.642	2.52	2.52	25220	25220
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12537	12537
glue	plastics	epoxy resin	-	0.062	0.09		948	
	noble metal	silver	7440-22-4	0.291	0.45	0.54	4470	5418
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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